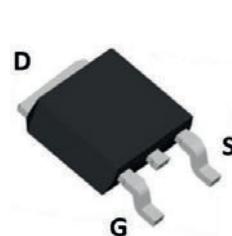
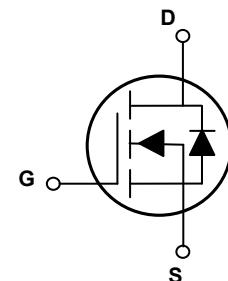


## Main Product Characteristics

$V_{(BR)DSS}$	600V
$R_{DS(ON)}$	0.88Ω (max.)
$I_D$	5A



TO-252 (DPAK)



Schematic Diagram

## Features and Benefits

- Advanced MOSFET process technology
- Ideal for high efficiency switched mode power supplies
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery



## Description

The GSJD60R880 utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supplies and a wide variety of other applications.

## Absolute Maximum Ratings ( $T_C=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Parameter.	Unit
Drain-Source Voltage	$V_{DS}$	600	V
Gate-to-Source Voltage	$V_{GS}$	$\pm 30$	V
Continuous Drain Current, @ Steady-State ( $T_C=25^\circ\text{C}$ )	$I_D$	5	A
Continuous Drain Current, @ Steady-State ( $T_C=100^\circ\text{C}$ )		3.3	A
Pulsed Drain Current	$I_{DM}$	20	A
Power Dissipation ( $T_C=25^\circ\text{C}$ )	$P_D$	42	W
		0.33	W/°C
Single Pulse Avalanche Energy <sup>1</sup>	$E_{AS}$	214	mJ
Body Diode Reverse Voltage Slope <sup>2</sup>	$dv/dt$	50	V/ns
MOS $dv/dt$ Reggedness <sup>3</sup>	$dv/dt$	100	V/ns
Junction-to-Ambient (PCB Mounted, Steady-State)	$R_{\theta JA}$	62.0	°C/W
Junction-to-Case	$R_{\theta JC}$	2.98	°C/W
Operating Junction and Storage Temperature Range	$T_J/T_{STG}$	-55 to + 150	°C

**Electrical Characteristics** ( $T_C=25^\circ\text{C}$  unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
<b>On / Off Characteristics</b>						
Drain-to-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}}=0\text{V}, I_D=250\mu\text{A}$	600	-	-	V
Drain-to-Source Leakage Current	$I_{\text{DSS}}$	$V_{\text{DS}}=600\text{V}, V_{\text{GS}}=0\text{V}$	-	-	200	nA
Gate-to-Source Forward Leakage	$I_{\text{GSS}}$	$V_{\text{DS}}=0\text{V}, V_{\text{GS}}=30\text{V}$	-	-	100	nA
		$V_{\text{DS}}=0\text{V}, V_{\text{GS}}=-30\text{V}$	-	-	-100	
Static Drain-to-Source On-Resistance	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}}=10\text{V}, I_D=2.5\text{A}, T_J=25^\circ\text{C}$	-	0.7	0.88	$\Omega$
		$V_{\text{GS}}=10\text{V}, I_D=2.5\text{A}, T_J=125^\circ\text{C}$	-	1.4	-	$\Omega$
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}}=V_{\text{GS}}, I_D=250\mu\text{A}$	2.0	-	4.0	V
<b>Dynamic and Switching Characteristics</b>						
Input Capacitance	$C_{\text{iss}}$	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=100\text{V}, f=1\text{MHz}$	-	304	-	pF
Output Capacitance	$C_{\text{oss}}$		-	20	-	
Reverse Transfer Capacitance	$C_{\text{rss}}$		-	1.8	-	
Total Gate Charge <sup>4,5</sup>	$Q_g$	$I_D=5\text{A}, V_{\text{DD}}=480\text{V}, V_{\text{GS}}=10\text{V}$	-	12	-	nC
Gate-to-Source Charge <sup>4,5</sup>	$Q_{gs}$		-	2.7	-	
Gate-to-Drain ("Miller") Charge <sup>4,5</sup>	$Q_{gd}$		-	6.3	-	
Turn-On Delay Time <sup>4,5</sup>	$t_{\text{d}(\text{on})}$	$V_{\text{DD}}=300\text{V}, V_{\text{GS}}=10\text{V}, R_G=25\Omega, I_D=5\text{A}$	-	9	-	nS
Rise Time <sup>4,5</sup>	$t_r$		-	16	-	
Turn-Off Delay Time <sup>4,5</sup>	$t_{\text{d}(\text{off})}$		-	32	-	
Fall Time <sup>4,5</sup>	$t_f$		-	24	-	
Gate Resistance	$R_g$	$f=1\text{MHz}$	-	3.6	-	$\Omega$
<b>Source-Drain Ratings and Characteristics</b>						
Continuous Source Current (Body Diode)	$I_S$	$T_C=25^\circ\text{C}$ , MOSFET symbol showing the integral reverse p-n junction diode.	-	-	5	A
Source Pulse Current	$I_{\text{SM}}$		-	-	20	A
Diode Forward Voltage	$V_{\text{SD}}$	$I_S=5\text{A}, V_{\text{GS}}=0\text{V}$	-	-	1.4	V
Reverse Recovery Time <sup>3</sup>	$T_{\text{rr}}$	$I_F=5\text{A}, V_{\text{GS}}=0\text{V}, \frac{dI_F}{dt}=100\text{A}/\mu\text{s}$	-	320	-	nS
Reverse Recovery Charge <sup>3</sup>	$Q_{\text{rr}}$		-	1.9	-	$\mu\text{C}$

Note:

1.  $L=79\text{mH}, I_{AS}=2.2\text{A}, V_{\text{DD}}=100\text{V}$ , starting temperature  $T_J=25^\circ\text{C}$ .
2.  $V_{\text{DS}}=0-400\text{V}, I_{\text{SD}}<=20\text{A}, T_J=25^\circ\text{C}$ .
3.  $V_{\text{DS}}=0-480\text{V}$ .
4. Pulse test: pulse width  $\leq 300\mu\text{s}$ , duty cycle  $\leq 2\%$ .
5. Essentially independent of operating temperature.

## Typical Electrical and Thermal Characteristic Curves

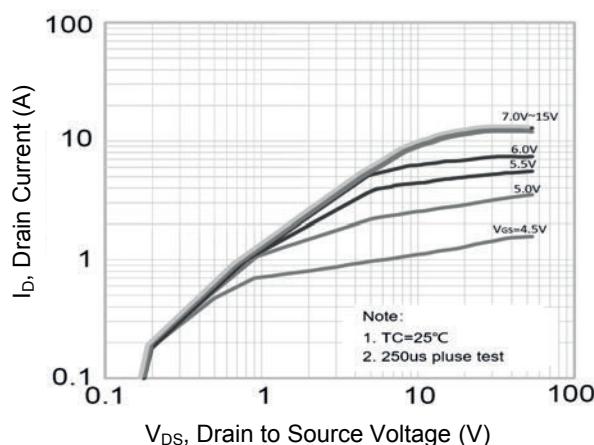


Figure 1. Typical Output Characteristics

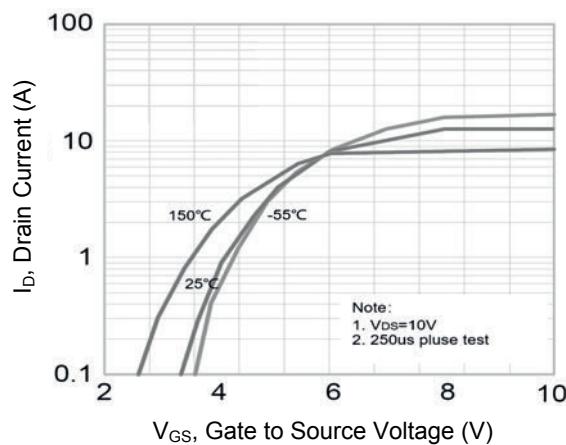


Figure 2. Transfer Characteristics

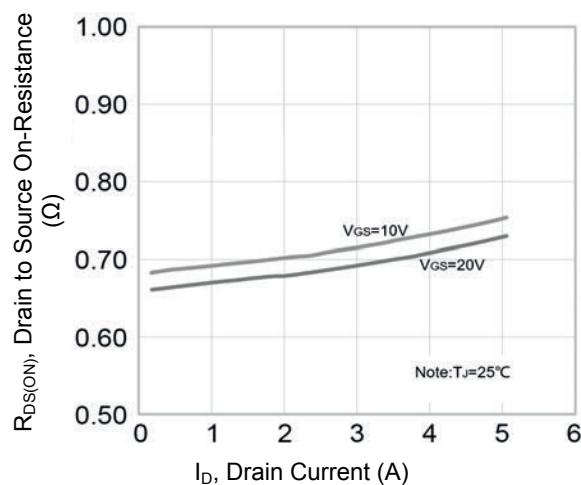


Figure 3.  $R_{DS(\text{ON})}$  Vs. Drain Current

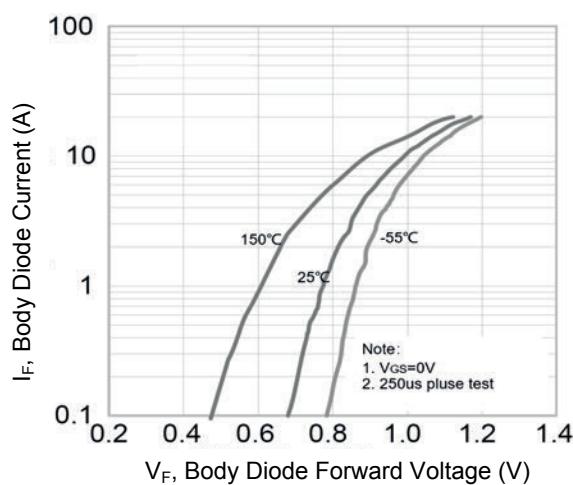


Figure 4. Body Diode Characteristics

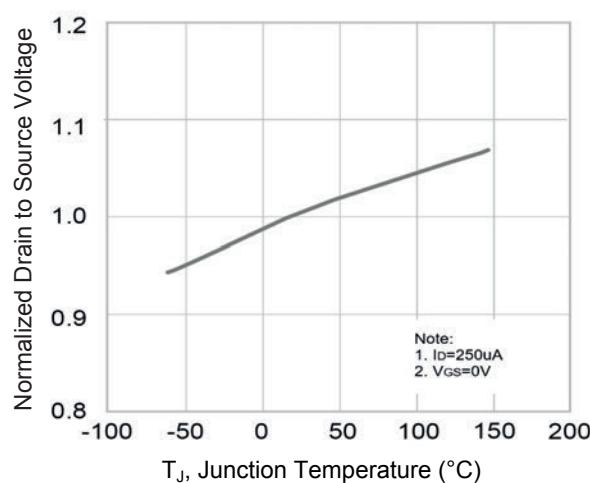


Figure 5. Normalized  $BV_{DSS}$  Vs.  $T_J$

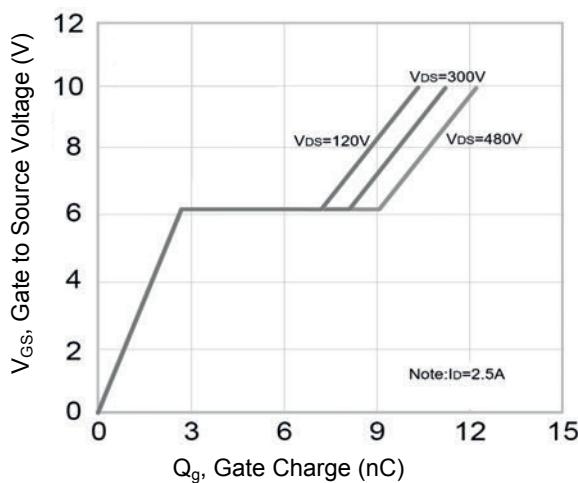
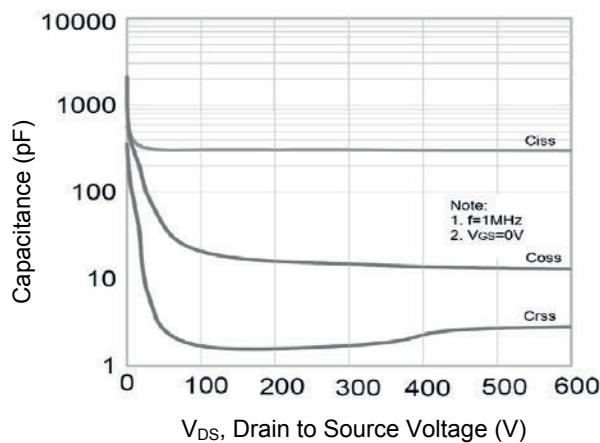
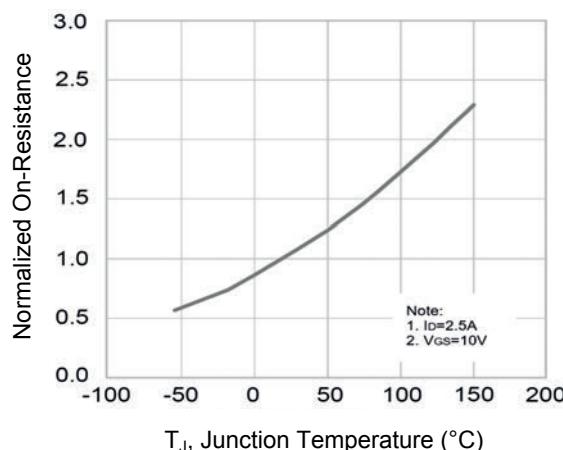


Figure 6. Gate Charge

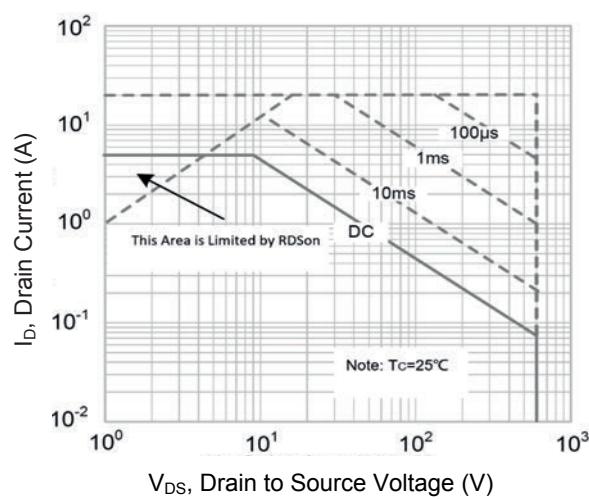
### Typical Electrical and Thermal Characteristic Curves



**Figure 7. Capacitance Characteristics**

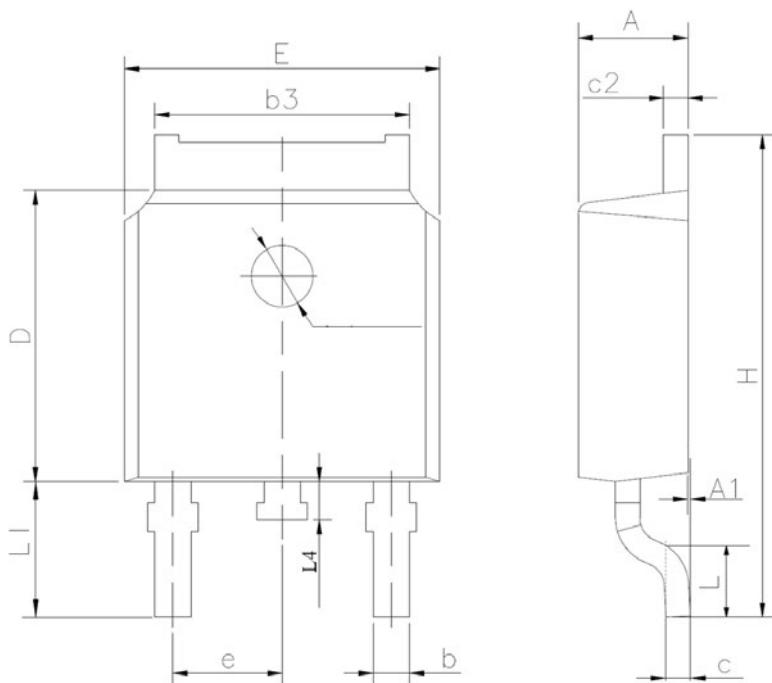


**Figure 8. Normalized  $R_{DS(ON)}$  Vs.  $T_J$**



**Figure 9. Safe Operation Area**

**Package Outline Dimensions TO-252(DPAK)**



<b>Symbol</b>	<b>Dimensions In Millimeters</b>		<b>Dimensions In Inches</b>	
	<b>Min.</b>	<b>Max.</b>	<b>Min.</b>	<b>Max.</b>
A	2.100	2.500	0.083	0.098
A1	0.000	0.127	0.000	0.005
b	0.660	0.890	0.026	0.035
b3	5.100	5.460	0.201	0.215
c	0.450	0.650	0.018	0.026
c2	0.450	0.650	0.018	0.026
D	5.800	6.400	0.228	0.252
E	6.300	6.900	0.248	0.272
e	2.300 TYP		0.091 TYP	
H	9.600	10.600	0.378	0.417
L	1.400	1.700	0.055	0.067
L1	2.900 REF		0.114 REF	
L4	0.600	1.000	0.024	0.039